Docket No.: GR 98 P 4137 P

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By:

Date: March 13, 2001

<u>TED STATES PATENT AND TRADEMARK OFFICE</u>

Applicant

Hans-Jürgen Hacke et al.

Appl. No.

09/761,594

Filed

January 16, 2001

Title

Semiconductor Device in Chip Format and Method for

Producing It

CLAIM FOR PRIORITY

Hon. Commissioner of Patents and Trademarks, Washington, D.C. 20231

Sir:

Claim is hereby made for a right of priority under Title 35, U.S. Code, Section 119, based upon the German Patent Application 198 32 706.4 filed July 14, 1998.

A certified copy of the above-mentioned foreign patent application is being submitted herewith.

Respectfully submitted,

D. 40,719

Date: March 13, 2001

Lerner and Greenberg, P.A.

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/mjb



BUNDESREPUBLIK DEUTSCHLAND



Prioritätsbescheinigung über die Einreichung einer Patentanmeldung

Aktenzeichen:

198 32 706.4

Anmeldetag:

14. Juli 1998

Anmelder/Inhaber:

Siemens AG, München/DE

Bezeichnung:

Halbleiterbauelement im Chip-Format

und Verfahren zu seiner Herstellung

IPC:

H 01 L 23/538

Die angehefteten Stücke sind eine richtige und genaue Wiedergabe der ursprünglichen Unterlagen dieser Patentanmeldung.

München, den 13. Februar 2001

Deutsches Patent- und Markenamt

Der Präsident

Im Auftrag

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Docket No.: GR 98 P 4137 D

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below.

Date:

October 19, 2005

UNITED STATES PATENT AND TRADEMARK OFFICE

Applic. No.

10/937,418

Confirmation No: 9046

JFW

Applicant

Hans-Jürgen Hacke, et al.

Filed

September 9, 2004

Art Unit

3762

Examiner

Terri L. Smith

Title

Method for Producing a Semiconductor Device in a

Chip Format

Docket No.

GR 98 P 4137 D : 24131

Customer No.

Date of Notice of Allowance : July 19, 2005

LETTER

Commissioner for Patents. P.O. Box 1450, Alexandria, VA 22313-1450

Sir:

Please note that the German Priority document number 198 32 706.4 dated July 14, 1998 was filed on March 15, 2001 in the U.S Patent Office. Please find enclosed copies of the following:

- 1) Claim for Priority
 - 2) The cover page of priority document; and
 - 3) The return postcard indicating receipt by the PTO.

Respectfully

Løcher **Ré**g. No. 41,947

Date: October 19, 2005 Lerner and Greenberg, P.A.

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March .13; .2001 ailidered the date on which	Size Prov. / Rule 53d CPA Cove Sheet WOO.	
DOCKET NO. GR. 98P. 41.37. P. Mailed March .13; .2001 A.PPLIC. NO	Applic pgs Rule 53b New Contin Div CIP /Rule 53c Prov. /Rule 53d CPA CIP pgs TM Design Dwgs inf. fm/ El Mehag Certif. Amend pgs Prel. Amend pgs El Letter Response pgs 37CFR1.116 Not. of Appeal Brief pgs Appndx pgs I.D.S. + Refs. Rassoc Pwr of Atty Specimen B Declaration Rassoc Pwr of Atty Specimen B Declaration Rassoc Pwr of Atty Specimen EVTOL / S. 3 3 Issue Fee Assignment EVTOL / S. 3 3 St. of Use Cert. of Corr. File rec. corr	(Patent Office. Please stamp and return to addressee on reverse side.)

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